



[10191/1711]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

	1	/ - N
ADD	licant	(S)

BECKER et al.

Confirmation No.: 3830

Serial No.

09/763,138

Filed

April 20, 2001

For

DEVICE AND METHOD FOR HIGH-RATE ETCHING A

SUBSTRATE USING A PLASMA ETCHING SYSTEM AND DEVICE AND METHOD FOR IGNITING A PLASMA AND

ADJUSTING UPWARD OR PULSING THE PLASMA POWER

Examiner

L. Schillinger

I hereby cartify that this correspondence is being deposited with the United States Postal Service as first class mail in an envel pe

addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on

TC/A.U.

2813

7/30/03

Atty's Reg. # _41,172

Customer No.:

26646

Atty's Signature

ŒNYON & KENYON

Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT TRANSMITTAL

SIR:

Please find an Amendment transmitted herewith for filing in the above-identified patent application. Applicant respectfully requests a one-month extension of time in which to respond to the office action dated March 31, 2003, for which a response period expiring on June 30, 2003 was set. The extended period expires on July 31, 2003.

Please charge the \$110.00 extension fee and any additional fees required to Deposit Account No. 11-0600. A duplicate copy of this Transmittal is enclosed.

Respectfully submitted,

90 90 98 933 -37 £ 150

Dated: 7/30/03

B7: LB 2 agut (B. No. 41,172)

Reg. No. 22,490

KENYON & KENYON One Broadway New York, NY 10004 (212) 425-7200